

US Patent & Trademark Office

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United States Patent Application Publication

20250253609

Kind Code

A1

Publication Date

August 07, 2025

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LIGHT EMITTING DEVICE

Abstract

A base includes: a bottom part having a bottom face, wherein the bottom face has a first region configured to support one or more semiconductor laser elements thereon and a second region configured to support a light reflective member and/or an optical member thereon; a lateral part surrounding the bottom face and extending upwards from the bottom face, wherein the lateral part has an uppermost face and includes a first stepped portion including a first upper face and a second stepped portion including a second upper face, wherein the first stepped portion faces the second stepped portion, and wherein the first upper face and the second upper face are disposed below the uppermost face; and one or more first metal films located on the first upper face of the first stepped portion.

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Appl. No.: 19/189400

Filed: April 25, 2025

Foreign Application Priority Data

JP	2019-220036	Dec. 05, 2019
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Related U.S. Application Data

parent US continuation 18808446 20240819 parent-grant-document US 12308604 child US 19189400

parent US continuation 18494190 20231025 parent-grant-document US 12107384 child US 18808446

parent US continuation 18146070 20221223 parent-grant-document US 11837845 child US

Publication Classification

Int. Cl.: H01S5/022 (20210101); H01S5/024 (20060101); H01S5/026 (20060101)

U.S. Cl.:

CPC H01S5/022 (20130101); H01S5/02461 (20130101); H01S5/0262 (20130101);

Background/Summary

CROSS-REFERENCE TO RELATED APPLICATION [0001] This application is a continuation of U.S. patent application Ser. No. 18/808,446, filed on Aug. 19, 2024, which is a continuation of U.S. patent application Ser. No. 18/494,190, filed Oct. 25, 2023 (now U.S. Pat. No. 12,107,384), which is a continuation of U.S. patent application Ser. No. 18/146,070, filed Dec. 23, 2022 (now U.S. Pat. No. 11,837,845), which is a continuation of U.S. patent application Ser. No. 17/111,194, filed Dec. 3, 2020 (now U.S. Pat. No. 11,569,634), which claims priority to Japanese Patent Application No. 2019-220036, filed on Dec. 5, 2019. The contents of these applications are hereby incorporated by reference in their entireties.

BACKGROUND

[0002] The present disclosure relates to a light emitting device.

[0003] As disclosed in Japanese Patent Publication No. 2014-157873, an optical module having a stepped portion in a recessed base and bonding wires connected to the stepped portion is known. Furthermore, in the optical module disclosed in this patent publication, a light receiving element in addition to a light emitting element is disposed in the recessed portion.

SUMMARY

[0004] A light emitting device according to the certain embodiments includes a base, a light emitting element, an electronic member, a first wiring region, a second wiring region, a plurality of wires. The base has a bottom face and a lateral part surrounding the bottom face and extending upwards from the bottom face. The lateral part includes a first stepped portion and a second stepped portion that are each defined by an inner lateral face and an upper face. A height of the second stepped portion from the bottom face is greater than a height of the first stepped portion from the bottom face. The light emitting element is disposed on the bottom face. The electronic member is disposed on the bottom face and configured to be irradiated by light emitted from the light emitting element. The first wiring region is located on the first stepped portion. The second wiring region is located on the second stepped portion. The plurality of wires are connected to the light emitting element and the electronic member. The plurality of wires include a first wire and a second wire. The first wire has a first end that is connected to the first wiring region, and a second end. The second wire has a first end that is connected to the second wiring region, and a second end. A position of the second end of the first wire relative to the bottom face, is lower than a position of the second end of the second wire relative to the bottom face.

[0005] According to the present disclosure, in a light emitting device including a light emitting element and an electronic member, the wire bonding of the light emitting element and the electronic member can be facilitated.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

[0006] FIG. 1 is a perspective view of a light emitting device according to a first embodiment.

[0007] FIG. 2 is a perspective view of the light emitting device according to the first embodiment from which the cover member is removed.

[0008] FIG. 3 is a top view of the light emitting device according to the first embodiment from which the cover member is removed.

[0009] FIG. 4 is a cross-sectional view of the light emitting device taken along line IV-IV in FIG. 3.

[0010] FIG. 5 is a perspective view of a light emitting device according to a second embodiment.

[0011] FIG. 6 is a perspective view of the light emitting device according to the second embodiment from which the cover member is removed.

[0012] FIG. 7 is a top view of the light emitting device according to the second embodiment from which the cover member is removed.

[0013] FIG. 8 is a cross-sectional view of the light emitting device taken along line VIII-VIII in FIG. 7.

[0014] FIG. 9 is a top view of an electronic member according to the second embodiment.

[0015] FIG. 10 is a perspective view of a light emitting device according to a third embodiment.

[0016] FIG. 11 is a top view of the light emitting device according to the third embodiment from which the cover is removed.

DETAILED DESCRIPTION

[0017] In the description and the accompanying claims, a polygon, such as a triangle, rectangle, or the like, including a shape subjected to processing, such as cutting angles, beveling, chamfering, rounding, or the like, will be referred to as a polygon. Moreover, the location of such processing is not limited to a corner (an end of a side). Rather, a shape subjected to processing in the middle of a side will similarly be referred to as a polygon. In other words, any polygon-based shape subjected to processing should be understood to be included in the interpretation of a “polygon” in the description and accompanying claims.

[0018] This similarly applies to any word describing a specific shape, such as a trapezoidal, circular, recessed, or projected shape, without being limited to a polygon. This also similarly applies to the sides defining such shapes. In other words, even if a corner or middle of a side is subjected to processing, the term “side” should be interpreted to include the processed portion. To distinguish a “polygon” or “side” that is intentionally not processed from a shape subjected to processing, the shape will be described by adding the phrase “exact,” such as “an exact rectangle.”

[0019] Moreover, in the description and accompanying claims, in the case in which there are a plurality of pieces of a certain constituent element and a distinction must be made, a word such as “first,” “second,” or the like might occasionally be added. The manner in which such a word is used in the description might not match the manner in which such a word is used in the claims if the subject to be distinguished or the perspective for such a distinction differs.

[0020] For example, in the case in which there are a plurality of an element denoted and distinguished by “first,” “second,” and “third” in the description, and a certain claim recites only those that are referred to as the “first” and “third” in the description, what are referred to as the “first” and “second” in the claim might correspond to what are referred to as the “first” and “third” in the description.

[0021] Certain embodiments of the present invention will be explained below with reference to the accompanying drawings. The embodiments described below are provided to give shape to the technical ideas of the present invention, and are not intended to limit the present invention. In the explanation below, the same designations and reference numerals denote the same or similar

members, and redundant explanations will be omitted as appropriate. The sizes and relative positions of the members shown in the drawings might be exaggerated for clarity of explanation.

First Embodiment

[0022] A light emitting device **1** according to a first embodiment will be explained. FIG. **1** to FIG. **4** are drawings illustrating a light emitting device **1**. FIG. **1** is a perspective view of the light emitting device **1**. FIG. **2** is a perspective view of the light emitting device **1** in the state in which the cover member **80** is not shown. FIG. **3** is a top view in the same state as in FIG. **2**. FIG. **4** is a cross-sectional view taken along line IV-IV in FIG. **3**.

[0023] The light emitting device **1** has a plurality of constituent elements including a base **10**, three semiconductor laser elements **20**, a submount **30**, an electronic member **40**, a support member **50**, an optical member **60**, a plurality of wires **70**, and a cover member **80** (see FIG. **4**, in particular, for the support member **50**).

[0024] In the light emitting device **1**, the three semiconductor laser elements **20**, the submount **30**, the electronic member **40**, the support member **50**, the optical member **60**, and the wires **70** are arranged in the space surrounded by the base **10** and the cover member **80**. In the light emitting device **1**, light is emitted by the three semiconductor laser elements **20** disposed in the space. Each constituent element will be explained first.

Base 10

[0025] The base **10** has an arrangement region in which other constituent element(s) are arranged, and lateral walls that surround the arrangement region. The base **10** has a recessed portion, which includes the arrangement region and the lateral walls. The recessed portion is depressed in the direction from the upper face to the lower face of the base **10**. In the present disclosure, the bottom of the recessed portion will be referred to as the bottom face of the base **10**. The bottom face of the base **10** can be a main portion of the arrangement region.

[0026] The periphery of the base **10** is rectangular in a top view. The periphery of the recessed portion is rectangular in the top view. Furthermore, in the top view, the rectangular periphery of the bottom face of the base **10** is smaller than the periphery of the recessed portion. It is not essential for any of these to have a rectangular periphery.

[0027] The base **10** has a bottom part **11** and lateral parts **12**. The bottom part **11** comprises the bottom face of the base **10**. The bottom part **11** includes the bottom face and the lower face of the base **10**. The lateral part **12** comprises the lateral walls of the base **10**. Accordingly, the lateral part **12** surrounds the bottom face of the base **10** as well as upwardly extending from the bottom face. Moreover, the lateral part **12** includes one or more outer lateral faces, one or more inner lateral faces, and an upper face meeting the outer lateral face(s) and the inner lateral face(s).

[0028] The number of inner lateral faces or the outer lateral faces depends on the shape surrounding the bottom face. For example, in the case in which the shape surrounding the bottom face is rectangular, inner lateral faces are formed to correspond to the four sides of the rectangle; i.e., there are a plurality of inner lateral faces. In the case in which the shape surrounding the bottom face is circular, one inner lateral face is formed to correspond to a circle; i.e., there is a single inner lateral face. The same is true for the outer lateral faces.

[0029] The base **10** has a plurality of stepped portions. A stepped portion is specified here as a portion composed only of an upper face and an inner lateral face(s) meeting the upper face and extending downwards therefrom. The stepped portions are included as parts of the lateral part **12** of the base **10**. Each of the stepped portions is provided between the bottom face and the upper face of the base **10**. In the top view, moreover, each stepped portion is formed between the periphery of the recessed portion and the periphery of the bottom face of the base **10**.

[0030] Each of the stepped portions is formed along the inner lateral face of the base **10** which meet the upper face of the base **10**. Accordingly, the upper face of each stepped portion meets the inner lateral face of the base **10** which meets the upper face of the base **10**. The steps formed by the stepped portions extend along the entire perimeter of one or more of the inner lateral faces that

surround the arrangement region of the base **10**. However, the steps formed by the stepped portions do not have to be formed along the entire perimeter.

[0031] The stepped portions include a first stepped portion **13** and a second stepped portion **15**. In the light emitting device **1** illustrated in the drawings, the stepped portions are configured as only of the first stepped portion **13** and the second stepped portion **15**, but can have one or more additional stepped portions.

[0032] The first stepped portion **13** and the second stepped portion **15** have different heights. In other words, the heights of the upper faces of the first stepped portion **13** and the second stepped portion **15** from the bottom face of the base **10** differ. In the case of the light emitting device **1** shown in the drawings, the second stepped portion **15** is positioned higher from the bottom face than the first stepped portion **13**. The base can have a first stepped portion **13** which is positioned higher than a second stepped portion **15**.

[0033] The first stepped portion **13** and the second stepped portion **15** are each formed along a portion of the inner lateral faces of the base **10** that meets the upper face of the base. Accordingly, the upper face of the first stepped portion **13** meets certain portions of the inner lateral faces of the base **10** that meet the upper face of the base, and the upper face of the second stepped portion **15** meets certain portions of the inner lateral faces of the base **10** that meet portions of the upper face of the base **10** that are different from those met by the upper face of the first stepped portion **13**.

[0034] In the top view, the total length of one or more of the inner lateral faces of the base **10** meeting the upper face thereof along which the first stepped portion **13** is formed is larger than the total length of the inner lateral faces along which the second stepped portion **15** is formed.

Moreover, the second stepped portion **15** is formed along a portion of the overall perimeter of the one or more inner lateral faces, and the first stepped portion **13** is formed along the remaining portion of the overall perimeter.

[0035] In the light emitting device **1** illustrated in the drawings, which has a rectangular periphery defined by four inner lateral faces in the top view, the total length of the portions along which the first stepped portion **13** is formed is equal to or larger than the sum of the lengths of the two long sides of the rectangle, but equal to or less than the sum of the two long sides and one short side of the rectangle. The length of the portion along which the second stepped portion **15** is formed is equal to or larger than the length of one short side of the rectangle, but equal to or less than the length of one long side of the rectangle.

[0036] One or more of the inner lateral faces of the first stepped portion **13** have lower sides that meet the bottom face of the base **10**. The inner lateral face of the second stepped portion **15** has lower side(s) that meets the base **10**. Because the stepped portions are formed so as to rise from the bottom face, the stepped portions can be provided in the positions near the arrangement region. The total length of the portions where the first stepped portion **13** meets the bottom face of the base **10** is larger than the length of the portion where the second stepped portion **15** meets the bottom face of the base **10**.

[0037] The lower sides of the inner lateral faces of the first stepped portion **13** do not meet the second stepped portion **15** except for the endpoints of the sides. At the endpoints, the inner lateral face of the second stepped portion **15** meets the bottom face of the base **10**.

[0038] The inner lateral face of the second stepped portion **15** has a lower side meeting the bottom face of the base **10** and a lower side meeting the upper face of the first stepped portion **13**. The length of the portion where the inner lateral face of the second stepped portion **15** meets the bottom face of the base **10** is larger than the length of the portions where the inner lateral face of the second stepped portion **15** meets the upper face of the first stepped portion **13**. In this manner, a large bottom face as well as an adequate arrangement region can be secured.

[0039] The height of the second stepped portion **15** from the bottom face of the base **10** is preferably in the range of from 1.2 to 3.0 times the height of the first stepped portion **13** from the bottom face of the base **10**. It is preferable for the height of the first stepped portion **13** to be

smaller than one half of the height from the bottom face to the upper face of the base **10**, and the height of the second stepped portion **15** to be larger than the height from the bottom face to the upper face of the base **10**.

[0040] One or more first wiring regions **14** are provided on the upper face of the first stepped portion **13**. In the light emitting device **1** illustrated in the drawings, a plurality of first wiring regions **14** are provided. The first wiring regions **14** are electrically connected through the interior of the base **10** to the wiring regions provided on the lower face of the base **10**. The wiring regions to be electrically connected to the first wiring regions **14** can be provided on the outer surfaces (upper face, outer lateral faces, and/or lower face) of the base **10**, without limiting the location to the lower face of the base **10**.

[0041] One or more second wiring regions **16** are provided on the upper face of the second stepped portion **15**. In the light emitting device **1** illustrated in the drawings, a plurality of second wiring regions **16** are provided. The second wiring regions **16** are electrically connected through the interior of the base **10** to the wiring regions disposed on the lower face of the base **10**. The wiring regions to be electrically connected to the second wiring regions **16** can be provided on the outer surfaces (upper face, outer lateral faces, and/or lower face) of the base **10**, without limiting the location to the lower face of the base **10**.

[0042] The base **10** can be formed using a ceramic as a main material. Examples of ceramics for use as the base **10** include aluminum nitride, silicon nitride, aluminum oxide, silicon carbide, and the like.

[0043] The base **10** can be formed in such a way that the bottom part **11** and the lateral part **12** are monolithic. Alternatively, the base can be formed in a manner that the bottom part **11** and the lateral part **12** are formed using different main materials and are joined. In this case, a metal can be used as a main material for the base portion **11**, and a ceramic as a main material for the lateral part **12**.

[0044] In this case, furthermore, the metal employed for the bottom part **11** is preferably one having good heat dissipation properties (higher thermal conductivity) than the ceramic employed for the lateral part **12**. For example, copper, aluminum, iron, as well as a composite material, such as copper-molybdenum, copper-diamond, copper-tungsten, or the like, can be used.

[0045] A metal film is disposed in the locations in the base **10** that correspond to the first wiring regions **14**, the wiring regions to be electrically connected thereto, the second wiring regions **16**, and the wiring regions to be electrically connected thereto. A metal material is also disposed at the locations in the interior of the base for electrical connection, which achieves the electrical connection.

Semiconductor Laser Element **20**

[0046] A semiconductor laser element **20** has a rectangular periphery in the top view. The lateral face meeting one of the two short sides of the rectangle serves as the emission face through which the light exits from the semiconductor laser element **20**. The upper face and the lower face of the semiconductor laser element **20** have larger areas than the emission face.

[0047] Moreover, a semiconductor laser element **20** is a multi-emitter having two emitters. An electrode shared by the two emitters is provided on one of the upper and lower faces of the semiconductor laser element **20**, and two electrodes corresponding to the emitters are provided on the other face.

[0048] The light (laser beam) emitted from each emitter of a semiconductor laser element **20** spreads, forming an elliptical far field pattern (hereinafter referred to as “FFP”) in a plane parallel to the emission face. FFP represents the shape and light intensity distribution of the emitted light at a location distant from the emission face.

[0049] In the present disclosure, the light passing through the center of an elliptical FFP, i.e., the light having the peak intensity in the FFP light intensity distribution, will be referred to as the light advancing along the optical axis. The light having an intensity of at least $1/e^2$ relative to the peak intensity value based on the light intensity distribution of an FFP will be referred to as the

main portion of the emitted light.

[0050] The shape of the FFP of the emitted light from a semiconductor laser element **20** is an ellipse that is longer in the stacking direction of the semiconductor layers including the active layer than in the layer direction perpendicular to the stacking direction of the semiconductor layers. The layer direction will be referred to as the lateral direction of the FFP, and the stacking direction will be referred to as the vertical direction of the FFP.

[0051] Based on an FFP light intensity distribution, the angle corresponding to the full width at half maximum of the light intensity distribution will be referred to as the divergence angle of light emitted from a semiconductor laser element. The divergence angle in the vertical direction of an FFP will be referred to as vertical divergence angle, and the divergence angle in the horizontal direction of an FFP will be referred to as horizontal divergence angle.

[0052] For a semiconductor laser element **20**, for example, a blue light emitting semiconductor laser element, a green light emitting semiconductor laser element, or a red light emitting laser element can be employed. A semiconductor laser element emitting light of a color other than these can be employed.

[0053] In the present disclosure, blue light refers to light having a peak emission wavelength in the **420 nm to 494 nm** range, green light refers to light having a peak emission wavelength in the **495 nm to 570 nm** range, and red light refers to light having a peak emission wavelength in the **605 nm to 750 nm** range.

[0054] Examples of blue or green light emitting semiconductor laser elements include semiconductor laser elements including nitride semiconductors. Examples of usable nitride semiconductors include GaN, InGaN, and AlGaN. Examples of usable red light emitting semiconductor laser elements include those that include InAlGaP-based, GaInP-based, GaAs-based, and AlGaAs-based semiconductors.

Submount **30**

[0055] A submount **30** is shaped as a rectangular cuboid having two opposing bonding faces. The distance between the two opposing bonding faces is smaller than the distance between the other two opposing faces. The shape of the submount **30** is not limited to a rectangular cuboid. The submount **30** can be formed with, for example, silicon nitride, aluminum nitride, or silicon carbide. A metal film is formed on the upper face of the submount **30**.

Electronic Member **40**

[0056] An electronic member **40** has a bonding face and a light-irradiated face. The bonding face and the light-irradiated face oppose to each other. The electronic member **40** is a part of the optical control unit that controls the light being irradiated on the light-irradiated face.

[0057] For an electronic member **40**, for example, a microelectromechanical system (hereinafter referred to by using the acronym, MEMS) can be employed. Alternatively, for example, a light receiving element such as a photodiode (hereinafter referred to by using the acronym, PD) can be used. The electronic member **40** can reflect at least 80% of the light irradiated on the light-irradiated face.

Support Member **50**

[0058] A support member **50** has a lower face, and an oblique face **51** that is oblique to the lower face. The oblique face **51** is not perpendicular or parallel to the lower face. For example, the oblique face **51** is formed as a plane forming an inclination angle of **45 degrees** to the lower face. The inclination angle is not limited to **45 degrees**. Furthermore, the support member **50** includes only the oblique face **51** or one or more additional oblique faces each oblique to the lower face of the support member **50**. In the case in which the support member **50** includes the oblique face **51** and the one or more oblique faces, the oblique face **51** is one having the largest area.

[0059] Furthermore, the oblique face **51** occupies at least 60% of the area of the support member **50** in the top view. Furthermore, in the top view, the width from the upper edge to the lower edge of the oblique face **51** is at least 60% of the width of the support member **50** in the same direction. In

other words, the support member **50** has the structure in which the oblique face **51** accounts for a major percentage in this direction.

[0060] The support member **50** can be formed of, for example, ceramics, glass, or metals. For example, ceramics such as aluminum nitride, glass such as quartz or borosilicate glass, and metals such as aluminum can be used. Alternatively, the support member can be formed by using Si or the like.

Optical Member **60**

[0061] An optical member **60** has a bonding face and a lens face **61**. The lens face **61** includes a lens shaped face. The optical member is oriented such that the lens face **61** becomes a lateral face in the case in which the bonding face is the lower face.

[0062] The lens face **61** has a shape in which a plurality of lenses are connected in a row. In the present embodiment, the lens face **61** is formed by connecting three lenses in a lateral side view. The optical member **60** can be formed by using glass, for example, BK 7 glass.

[0063] Wire **70**

[0064] A wire **70** has a linear shape with both ends as bonding portions. In other words, the wire has bonding portions at both ends of the linear portion to be bonded to other constituent elements. A wire **70** is, for example, a metal wire. For example, gold, aluminum, silver, copper, or the like can be used.

Cover Member **80**

[0065] A cover member **80** is a plate-shaped rectangular cuboid having a lower face and an upper face. The shape does not have to be a rectangular cuboid. Furthermore, the cover member **80** has light transmissivity. Accordingly, the cover member **80** can also be referred to as a light transmissive member. A light transmissive member without having a role as a cover can be used.

[0066] In the present application, transmissivity is defined as having light transmissivity of at least 80%. It does not have to have transmissivity of at least to 80% for light of all wavelengths. The cover member **80** can have a non-transmissive region (the region having no or less light transmissivity) in one portion.

[0067] The cover member **80** can be formed of sapphire. Sapphire is a material having light transmissivity, a relatively high refractive index, and relatively high strength. Besides sapphire, glass, for example, can be used.

Light Emitting Device **1**

[0068] A light emitting device **1** will be explained next. The light emitting device **1** includes a base **10**, three semiconductor laser elements **20** disposed on the base **10**, an electronic member **40** disposed on the base **10**, and wires **70**. The wires **70** includes a plurality of first wires **71** for electrically connecting the three semiconductor laser elements **20**, and a plurality of second wires **72** for electrically connecting the electronic member **40**.

[0069] In the light emitting device **1**, the three semiconductor laser elements **20** are disposed on the base **10** via a submount **30**. The semiconductor laser elements **20** can be disposed directly on the bottom face of the base **10** without interposing a submount **30**. In this case, the outer shape of each semiconductor laser element **20** may be changed in order to adjust the light emitting position (height) of the emission face.

[0070] The electronic member **40** is disposed on the base **10** via a support member **50**. It can be directly disposed on the bottom face of the base **10** without interposing a support member **50**. In this case, the shape of the electronic member **40** may be changed in order to adjust the position (height) and the direction (inclination) of the light-irradiated face **41**.

[0071] Furthermore, the light emitting device **1** includes an optical member **60** disposed on the base **10**. Moreover, the light emitting device **1** includes a cover member **80** which is joined to the base **10** and seals the space in which the three semiconductor laser elements **20** are disposed.

[0072] The three semiconductor laser elements **20** are disposed on the bottom face of the base **10**. Accordingly, it can be said that they are disposed on the bottom part **11** of the base **10**. The three

semiconductor laser elements **20** are arranged in a row such that their emission faces face the same direction. The lateral faces meeting the emission faces face one another between adjacent semiconductor laser elements **20**.

[0073] The three semiconductor laser elements **20** can be composed of, for example, a blue light emitting semiconductor laser element, a green light emitting semiconductor laser element, and a red light emitting semiconductor laser element. They can be composed of multiple semiconductor laser elements emitting light of the same color, or include a semiconductor laser element emitting light of another color.

[0074] The number of semiconductor laser elements **20** disposed in a light emitting device **1** does not have to be three. The number can be more than three or less than three. Instead of the semiconductor laser elements **20**, other light emitting elements such as LEDs can be used. The light emitting device **1** has at least one light emitting element.

[0075] The submount **30** is bonded to the semiconductor laser elements **20** using one bonding face, and is bonded to the bottom face of the base **10** using the other bonding face. Accordingly, it can be said that the submount is disposed on the bottom part **11** of the base **10**.

[0076] The light emitting device **1** can have a plurality of submounts **30**. In this case, the number of semiconductor laser elements **20** bonded to one submount **30** does not have to be three, i.e., it can be two or one. In other words, in the light emitting device **1**, the submount **30** or each of the submounts **30** is bonded to at least one semiconductor laser element **20**.

[0077] The electronic member **40** can be a MEMS. The electronic member **40** is disposed on the bottom face of the base **10**. Accordingly, it can be said that the electronic member is arranged on the bottom part **11** of the base **10**. The electronic member **40** is oriented such that the light emitted by the semiconductor laser elements **20** irradiates the light-irradiated face **41**. Furthermore, the entire main portion of the light emitted by each of the three semiconductor laser elements **20** irradiates the light-irradiated face **41**.

[0078] The light-irradiated face **41** upwardly reflects the laterally emitted light from the semiconductor laser elements **20**. Accordingly, the light-irradiated face **41** is inclined relative to the emission faces and the optical axes. The light-irradiated face **41** is inclined at an angle of **10** to **80** degrees relative to the bottom face of the base **10**.

[0079] The electronic member **40** is joined to the oblique face **51** of the support member **50**. The support member **50** is positioned such that the oblique face **51** faces in the direction toward the semiconductor laser elements **20**. Accordingly, it can be said that the electronic member **40** is disposed on the oblique face **51**. Arranging the electronic member **40** via the support member **50** can simplify the shape of the electronic member **40**. The support member **50** is preferably formed of a material more easily formable than the electronic member **40**.

[0080] The lower face of the support member **50** is joined to the bottom face of the base **10**. Accordingly, it can be said that the support member is disposed on the bottom part **11** of the base **10**. Joining the lower face of the support member **50** to the bottom face of the base **10** allows the oblique face **51** to incline relative to the bottom face.

[0081] The optical member **60** is disposed between the emission faces of the semiconductor laser elements **20** and the light-irradiated face **41** of the electronic member **40** in the top view.

Furthermore, the optical member **60** is disposed to allow the lens face **61** to face in a direction toward the light-irradiated face **41**. The three lenses individually correspond to the light emitted from the three semiconductor laser elements **20**. The lenses respectively collimates the light from the semiconductor laser elements **20**. Accordingly, the collimated light irradiates the MEMS employed as the electronic member **40**.

[0082] The MEMS reflects the irradiated light upwards. The main portions of the light from the semiconductor laser elements **20** emitted towards the electronic member **40** in a predetermined direction advance in a different direction from this. The MEMS reflects only the necessary portion of the irradiated light.

[0083] The light emitted by the semiconductor laser elements **20** diverges and is collimated by the optical member **60** before hitting the electronic member **40**. Accordingly, the light-irradiated face **41** needs to extend higher than the emission points of the semiconductor laser elements **20**. Accordingly, the height of the electronic member **40** is higher than the heights of the semiconductor laser elements **20**.

[0084] The light-irradiated face **41** is longer at the central portion in the direction perpendicular to the bottom face of the base **10** and becomes shorter as the distance from the center increases. Accordingly, among the three semiconductor laser elements **20**, one having the largest vertical divergence angle in the direction perpendicular to the bottom face is positioned in the center. This can effectively utilize the light-irradiated face **41**. However, the arrangement of the semiconductor laser elements **20** is not limited to this.

[0085] In the light emitting device **1** illustrated in the drawings, the wire bonding locations for the electronic member **40** are higher than the wire bonding locations for the semiconductor laser elements **20**. The light emitting device **1** shown in the drawings can improve wire bonding convenience by using the lower first stepped portion **13** for wire bonding the semiconductor laser elements **20**, and the higher second stepped portion **15** for wire bonding the electronic member **40** positioned higher than the semiconductor laser elements **20**.

[0086] In the state in which the submount **30** is disposed on the bottom face of the base **10**, the height of the bonding face of the submount **30** for bonding the semiconductor laser elements **20** from the bottom face of the base **10** is preferably the same as, or lower than, the height of the first stepped portion **13** of the base **10**. The heights of the upper faces of the semiconductor laser elements **20** from the bottom face of the base **10** preferably exceed or are higher than the height of the first stepped portion **13** of the base **10**. This can facilitate connection with the first wires **71**.

[0087] In the state in which the electronic member **40** is disposed on the bottom face of the base **10**, the height of the electronic member **40** exceeds the height of the first stepped portion **13**. The heights of the bonding locations for the second wires **72** in the electronic member **40** exceed the height of the first stepped portion **13**. Furthermore, the bonding locations of the second wires **72** for the electronic member **40** are higher positioned than the upper edges of the main portions of the light irradiated on the light-irradiated face **41**.

[0088] The maximum height (the height of the upper edge) of the light-irradiated face **41** of the electronic member **40** exceeds the height of the first stepped portion **13** and the heights of the semiconductor laser elements **20**. The minimum height (the height of the lower edge) of the light-irradiated face **41** is smaller than the height of the first stepped portion **13** and the heights of the semiconductor laser elements **20**.

[0089] In the state in which the semiconductor laser elements **20** and the electronic member **40** are disposed on the base **10**, the inner lateral faces of the base **10** can be divided into two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in series, and two opposing planar regions between which the semiconductor laser elements **20** and electronic member **40** are interposed in parallel. In the case in which the recessed portion has a rectangular periphery in the top view as in the case of the light emitting device **1**, the inner lateral faces corresponding to the four sides of the rectangle constitute the planar regions.

[0090] The inner lateral faces of the first stepped portion **13** can be formed in the two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in parallel. This can facilitate the positioning of the first wiring regions **14** while avoiding the optical paths of the main portions of the light.

[0091] The inner lateral face of the second stepped portion **15** can be formed in a first of the two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in series, the first of the two opposing planar region being located at a shorter distance from the electronic member **40** than from the semiconductor laser elements **20**. Positioning the second stepped portion **15** in the rear of the light-irradiated face **41** of the electronic

member **40** can more effectively prevent the stepped portion from intruding the optical paths of the light reflected by the electronic member **40**.

[0092] Furthermore the inner lateral face of the first stepped portion **13** can be formed in a second of the two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in series, the second of the two opposing planar regions being located at a greater distance from the electronic member **40** than from the semiconductor laser elements **20**. This can provide the first wiring regions **14** in the region extending in the opposite direction to the direction of travel of the light from the emission faces of the semiconductor laser elements **20**, thereby facilitating the bonding of the wires **70** while avoiding the optical paths of the main portions of the light.

[0093] In the light emitting device **1** illustrated in FIG. **3**, the first stepped portion **13** has two opposing inner lateral faces between which the semiconductor laser elements **20** and the electronic member **40** are interposed in parallel, and one inner lateral face in the second of the two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in series, the second of the two planar regions being located at a greater distance from the electronic member **40** than from the semiconductor laser elements **20**. The second stepped portion **15** has one inner lateral face in the first of the two opposing planar regions between which the semiconductor laser elements **20** and the electronic member **40** are interposed in series, the first of the two planar regions being located at a shorter distance to the electronic member **40** than to the semiconductor laser elements **20**.

[0094] The bonding portion at one end of each first wire **71** is bonded to a first wiring region **14**, and the other bonding portion is bonded to the upper face of a semiconductor laser element **20** or the upper face of the submount **30**. A bonding region for bonding with a first wire **71** is provided on the upper face of a semiconductor laser element **20** or the upper face of the submount **30**.

[0095] It is not essential to connect all of the first wires **71** (i.e., all wires used to electrically connect the three semiconductor laser elements **20**) to the first wiring regions **14**. The bonding portion(s) of one or plural first wires **71** at one end are connected to the first wiring region(s) **14**.

[0096] The bonding portion at one end of a second wire **72** is connected to a second wiring region **16**. The bonding portion at the other end is connected to the electronic member **40**. The electronic member **40** has a bonding region for connection with a second wire **72**.

[0097] It is not essential to connect all of the second wires **72** (i.e., all wires used to electrically connect the electronic member **40**) to the second wiring regions **16**. The bonding portion(s) of one or plural second wires **72** at one end are connected to the second wiring region(s) **16**.

[0098] The bonding region of the electronic member **40** is located higher than the center of the light-irradiated face **41**. The height of the bonding region of the electronic member **40** is higher than the bonding regions of the semiconductor laser elements **20** and the submount **30**. The bonding region of the electronic member **40** is preferably located in the vicinity of the upper edge of the surface where the light-irradiated face **41** is provided. Providing the bonding region in such a location can facilitate the bonding of the second wires **72**.

[0099] The bonding region for the electronic member **40** with the second wires **72** is preferably positioned at a distance from the light-irradiated face **41**. Providing the bonding region outside of the light-irradiated face **41** can facilitate the installation of the second wires **72** without blocking the light from the semiconductor laser elements **20**.

[0100] In the light emitting device **1** illustrated in the drawings, the number of wires to electrically connect the semiconductor laser elements **20** is larger than the number of wires to electrically connect the electronic member **40**. Because there are more first wires **71** than second wires **72**, the number of first wiring regions **14** is larger than the number of the second wiring regions **16**.

[0101] In the light emitting device **1** illustrated in the drawings, furthermore, the total length of the portions along the first stepped portion **13** is larger than the length of the portion along the second stepped portion **15**. A longer stepped portion provided for disposing a larger number of wiring

regions can improve a wire bonding convenience. Accordingly, the magnitude relation between the numbers of the first and second wiring regions is consistent with the magnitude relation between the lengths along the first stepped portion **13** and the second stepped portion **15**.

[0102] The cover member **80** is disposed on the upper face of the base **10**. It thus can be said that the cover member is disposed on the lateral part **12** of the base **10**. The cover member **80** is bonded to the upper face of the base **10** positioned higher than the second stepped portion **15**. The cover member **80** when joined to the base **10** creates a closed space enclosed by the base **10** and the cover member **80**. This space is where the semiconductor laser elements **20** are arranged.

[0103] Furthermore, joining the cover member **80** to the base **10** under predetermined atmospheric conditions can create a hermetically sealed space. Creating a hermetically sealed space for arranging the semiconductor laser elements **20** can reduce quality degradation attributable to dust.

[0104] In the light emitting device **1**, the MEMS used as the electronic member **40** can control the light exiting the light emitting device **1** through the cover member **80**. The cover member **80** has light transmissivity for the light emitted from the semiconductor laser elements **20**. The optical control unit can be realized by electrically connecting the electronic member **40** and a control mechanism provided outside of the light emitting device **1** via a wiring region of the base **10**.

[0105] As disclosed above, in the light emitting device **1**, because the bonding positions for the semiconductor laser elements **20** and the bonding positions for the electronic member **40** for electrical connection have different heights, the connection of the wires **70** is facilitated by forming the stepped portions which have different heights in the base **10**. This can facilitate wire bonding.

[0106] Based on such a technical idea, a light emitting device according to the present invention is not limited to the first embodiment. In the light emitting device **1**, the first wires **71** for electrically connecting the semiconductor laser elements **20** are bonded to the first stepped portion **13** which is the lower positioned stepped portion, and the second wires **72** for electrically connecting the electronic member **40** are bonded to the second stepped portion **15** which is the higher positioned stepped portion. This is because the bonding positions for the electronic member **40** are higher than the bonding positions for the semiconductor laser elements **20**. However, if the bonding positions for the semiconductor laser elements **20** are higher than the bonding positions for the electronic member **40**, the first wires **71** can preferably be bonded to the second stepped portion **15** and the second wires **72** to the first stepped portion **13**.

[0107] In other words, one end of a first wire **71** is bonded to either a first wiring region **14** or second wiring region **16**, and one end of a second wire **72** is bonded to the other of the first wiring region **14** and the second wiring region **16**. Furthermore, the other end of the wire between the first wire **71** and the second wire **72**, the end bonded to the first wiring region **14** is bonded at a lower position from the bottom face of the base **10** than the other end of the wire bonded to the second wiring region **16**. Furthermore, the other end of the wire between the first wire **71** and the second wire **72**, the other end bonded to the second wiring region **16** is positioned higher from the bottom face of the base **10** than the first wiring region **14**.

Second Embodiment

[0108] A light emitting device **2** according to a second embodiment will be explained. FIG. 5 to FIG. 9 are drawings explaining an exemplary embodiment of the light emitting device **2**. FIG. 5 is a perspective view of the light emitting device **2**. FIG. 6 is a perspective view of the light emitting device **2** in the state where the cover member **80** is removed. FIG. 7 is a top view in the same state as in FIG. 6. FIG. 8 is a cross-sectional view taken along line VIII-VIII in FIG. 7. FIG. 9 is a top view when the electronic member **40** according to the second embodiment is viewed from the light-irradiated face. The ellipses in FIG. 9 indicate the regions irradiated by the main portions of the light from the semiconductor laser elements **20**. The broken lines indicate the major diameters of the ellipses.

[0109] The light emitting device **2** includes, as constituent elements, a base **10**, three semiconductor laser elements **20**, a submount **30**, an electronic member **40**, a support member **50**,

wires **70**, and a cover member **80**. The light emitting device **2** according to the second embodiment differs from the light emitting device **1** according to the first embodiment by not having an optical member **60**. Furthermore, it differs from the light emitting device **1** according to the first embodiment such that the electronic member is a PD.

[0110] The light emitting device **2** illustrated in the drawings has the larger number of first wires **71** than the light emitting device **1** shown in FIG. **3**. In the light emitting device **2** according to the second embodiment, the three semiconductor laser elements **20** are individually electrically connected such that the outputs can be individually adjusted. Each semiconductor laser element **20** is a multi-emitter having two emitters.

[0111] In the light emitting device **2**, light receiving regions **242** each corresponding to the light emitted by the three semiconductor laser elements **20** are provided in the light-irradiated face **241** of the electronic member **40**. A portion of the light irradiated at each light receiving region **242** is received while the remaining portion is reflected upwards. It is preferable to reflect at least 90% of the light in order to allow the device to output a large amount of light. In the case of the light emitting device **2**, three light receiving regions **242** are arranged in a row in the same direction in which the three semiconductor laser elements **20** are arranged in a row.

[0112] One light receiving region **242** corresponds to one semiconductor laser element **20**, and the light receiving regions **242** are separated. In other words, the light receiving regions **242** are spaced, not overlapping. A bonding region for a second wire **72** for electrical connection is provided in each light receiving region **242**.

[0113] As shown in FIG. **9**, the electronic member **40** has, as the bonding regions for the second wires **72**, first bonding regions **243** provided for each light receiving region, and one second bonding region **244** shared by the multiple light receiving regions.

[0114] All of the first bonding regions **243** and the second bonding region **244** are provided above the regions to which the main portions of the light from the semiconductor laser elements **20** irradiate. In other words, in the light emitting device **2**, the bonding regions are disposed in the positions more distant than the regions irradiated by the main portions of the light from the semiconductor laser elements **20**.

[0115] In the top view, each light receiving region **242** has a laterally smaller width portion at the upper edge. Specifically, each light receiving region has a shape that has a notched corner at the upper edge. The shape and the position of the laterally narrower width portion are consistent among the light receiving regions **242**.

[0116] The first bonding regions **243** are disposed in the areas made available by the reduced width portions of the light receiving regions. A first bonding region **243** of a light receiving region **242** laterally projects from the light receiving region **242**. In the case in which another light receiving region **242** is provided adjacent thereto in the projecting direction, the projected portion is disposed in the area made available by the reduced width portion of the adjacent light receiving region **242**.

[0117] The first bonding regions **243** are not provided on the straight lines extending along the major axes of the main portions of the light irradiating the light receiving regions **242**. In other words, the first bonding regions **243** are provided in the locations that avoid these straight lines. As shown in FIG. **7** and FIG. **8**, the second wires **72** bonded to the first bonding regions **243** extend upwards therefrom and then bonded to the second wiring regions **16**. Avoiding the straight lines extending along the major diameters of the beams can inhibit the second wires **72** from blocking the light reflected by the electronic member **40**.

[0118] A first bonding region **243** arranged between two light receiving regions **242** is provided between the straight lines extending along the major axes of the major portions of light irradiating the two light receiving regions **242**. In other words, the first bonding region **243** does not extend beyond the two straight lines. This can allow the second wire **72** to readily avoid blocking the light reflected by an adjacent light receiving region **242**.

[0119] Furthermore, a first bonding region **243** projects from one of two opposing adjacent and

closest sides of two adjacent light receiving regions **242**, and the straight line extending along the other side goes through the first bonding region **243**. Such a layout can provide the first bonding regions **243** such that the light receiving regions **242** are in close proximity to one another, thereby contributing to a reduction in the size of the light emitting device **2**.

[0120] Moreover, in the top view, the second bonding region **244** is disposed in the vicinity of the upper edge and on one of the sides of the electronic member **40** opposite the projecting direction of the first bonding regions **243**. The second bonding region **244** is not disposed on the straight line extending along the major axis of the major portion of the beam irradiating the light receiving region **242** closest to the second bonding region **244**.

[0121] The structure is not limited to one in which each semiconductor laser element **20** corresponds to a light receiving region, i.e., one light receiving region can be provided to receive the lights from multiple semiconductor laser elements **20**. A single or plural light receiving regions can be provided in the light-irradiated face **241**.

[0122] In the light emitting device **2**, the PD employed as the electronic par **40** can receive a predetermined percentage of the light irradiating the light-irradiated face **241**. The optical control unit can calculate the amount of light output by the light emitting device **2** and the amount of light reflected by the electronic member **40** based on the amount of light received. Based on the calculation results, various controls can be performed such as an adjustment of the intensity of light emitted by the semiconductor laser elements **20**.

Third Embodiment

[0123] FIG. **10** is a perspective view of a light emitting device **3** according to a third embodiment. FIG. **11** is a top view of the light emitting device **3** shown in FIG. **10** in the state where the cover member **80** is removed.

[0124] The light emitting device **3** includes, as constituent elements, a base **310**, three semiconductor laser elements **20**, a submount **30**, an electronic member **40**, a support member **50**, wires **70**, and a cover member **80**. As compared to the base **10** according to the first and second embodiments, positions of the stepped portions are different in the light emitting device **3** according to the third embodiment. Furthermore, as compared to the light emitting devices **1** and **2**, the light emitting device **3** has a fewer number of first wiring regions **14** that need to be secured.

[0125] The number of the first wiring regions **14** to be secured is affected by, for example, the number of semiconductor laser elements **20**. In the case of making the semiconductor laser elements **20** independently operable, the number of necessary wiring regions increases as the number of semiconductor laser elements **20** increases. Assuming that the wiring regions are provided in the first stepped portion described above, the number of first wiring regions **14** would increase.

[0126] For example, the number of the first wiring regions **14** to be secured can also be affected by the number of emitters each semiconductor laser element **20** has. In the case of making the emitters of the semiconductor laser elements **20** independently operable, the number of necessary wiring regions increases as the number of emitters increases. Assuming that such wiring regions are provided in the first stepped portion, the number of the first wiring regions **14** would increase.

[0127] In the light emitting device **3** illustrated in the drawings, each of the three semiconductor laser elements **20** has a single emitter. The number of the first wiring regions can vary depending on not only this, but on other factors. For example, there are instances where protective devices such as Zener diodes are provided to protect the semiconductor laser elements **20**.

[0128] Depending on the number of necessary first wiring regions, the area to be secured as the first stepped portion changes. Reducing the size of the base by appropriately designing the area where the first stepped portion is formed can lead to size reduction of the light emitting device.

[0129] In the lateral part **312** of the light emitting device **3**, no inner lateral face of the first stepped portion **313** is provided in the first of the two opposing planar regions between which the semiconductor laser elements **20** and electronic member **40** are interposed in series, the first of the

two opposing planar regions having a smaller distance from the electronic member **40** than from the semiconductor laser elements **20**. This can allow for a design of a small light emitting device. [0130] In the light emitting device **3** illustrated in the drawings, the first stepped portion **313** has two opposing inner lateral faces between which the semiconductor laser elements and the electronic member are interposed in parallel. No stepped portion defining an inner lateral face is provided in the second of the two opposing planar regions between which the semiconductor laser elements **20** and electronic member **40** are interposed in series, the second of the two opposing planar regions having a larger distance from the electronic member **40** than from the semiconductor laser elements **20**.

[0131] In the light emitting device **3**, the first stepped portion **313** is formed in the regions that do not intersect any straight line perpendicular to the emission faces of the semiconductor laser elements **20** while passing through the three semiconductor laser elements **20** in the top view.

[0132] Light emitting devices according to certain embodiments have been described above, but light emitting devices according to the present invention are not strictly limited to those described above. In other words, the present invention can be achieved without being limited to the external shapes and structures of the light emitting devices disclosed by the embodiments. Furthermore, the present invention is applicable to a device without making it essential to necessarily include all of the constituent elements of the described embodiments. For example, in the event that a certain component of a light emitting device included in any of the embodiments is not recited in the claims, the claimed invention can still be applicable in view of the design flexibility of a person of ordinary skill in the art for such a component through the use of an alternative, an omission, a change in shapes or materials employed, or the like.

[0133] The light emitting devices disclosed with reference to the embodiments described above can be used in head-mounted displays, projectors, automotive headlights, lighting fixtures, displays, and the like.

Claims

1. A base comprising: a bottom part having a bottom face, wherein the bottom face has a first region configured to support one or more semiconductor laser elements thereon and a second region configured to support a light reflective member and/or an optical member thereon; and a lateral part surrounding the bottom face and extending upwards from the bottom face, wherein the lateral part has an uppermost face and comprises a first stepped portion including a first upper face and a second stepped portion including a second upper face, wherein the first stepped portion faces the second stepped portion, and wherein the first upper face and the second upper face are disposed below the uppermost face; one or more first metal films located on the first upper face of the first stepped portion, wherein: in a top view, the first upper face and the second upper face are disposed inward of the uppermost face, the second region is spaced apart from the first region in the first direction, the first upper face is spaced apart from the second upper face in the first direction, and the first region and the second region are disposed between the first upper face and the second upper face.
2. The base according to claim 1, wherein: a height of the first stepped portion from the bottom face is different from a height of the second stepped portion from the bottom face.
3. The base according to claim 2, wherein: the height of the first stepped portion from the bottom face is higher than the height of the second stepped portion from the bottom face.
4. The base according to claim 1, further comprising: one or more second metal films located on the second upper face of the second stepped portion.
5. The base according to claim 4, wherein: the one or more second metal films are to be electrically connected to the one or more semiconductor laser elements.
6. The base according to claim 1, wherein: the uppermost face is a planar face to which a cover

member is bonded.

7. The base according to claim 1, wherein: in a top view, a periphery of the base is rectangular.

8. The base according to claim 7, wherein: the lateral part comprises a third stepped portion including a third upper face and a fourth stepped portion including a fourth upper face, the first stepped portion faces the second stepped portion, and in a top view, the first upper face and the second upper face are disposed inward of the uppermost face, the first region and the second region are disposed between the third upper face and the fourth upper face, the first upper face is directly adjacent to the third upper face and the fourth upper face, and the second upper face is directly adjacent to the third upper face and the fourth upper face.

9. The base according to claim 1, further comprising: the first region is configured to support at least three semiconductor laser elements.

10. A light emitting device comprising: one or more semiconductor laser elements; a light reflective member and/or an optical member; a base having a bottom part and a lateral part, wherein the bottom part has a bottom face including a first region on which the one or more semiconductor laser elements are disposed and a second region on which the light reflective member and/or an optical member are disposed, wherein the lateral part surrounds the bottom face and extends upwards from the bottom face, wherein the lateral part has an uppermost face and comprises a first stepped portion including a first upper face and a second stepped portion including a second upper face, wherein the first stepped portion faces the second stepped portion, and wherein the first upper face and the second upper face are disposed below the uppermost face; and one or more first metal films located on the first upper face of the first stepped portion, wherein: in a top view the first upper face and the second upper face are disposed inward of the uppermost face, the second region is spaced apart from the first region in the first direction, the first upper face is spaced apart from the second upper face in the first direction, and the first region and the second region are disposed between the first upper face and the second upper face.

11. The light emitting device according to claim 10, wherein: a height of the first stepped portion from the bottom face is different from a height of the second stepped portion from the bottom face.

12. The light emitting device according to claim 11, wherein: the height of the first stepped portion from the bottom face is higher than the height of the second stepped portion from the bottom face.

13. The light emitting device according to claim 10, further comprising: one or more second metal films located on the second upper face of the second stepped portion.

14. The light emitting device according to claim 13, wherein: the one or more second metal films are electrically connected to the one or more semiconductor laser elements.

15. The light emitting device according to claim 10, further comprising: a cover member bonded to the uppermost face, wherein: the uppermost face is a planer face.

16. The light emitting device according to claim 10, wherein: in a top view, a periphery of the base is rectangular.

17. The light emitting device according to claim 16, wherein: the lateral part comprises a third stepped portion including a third upper face and a fourth stepped portion including a fourth upper face, the first stepped portion faces the second stepped portion, and in a top view, the first upper face and the second upper face are disposed inward of the uppermost face, the first region and the second region are disposed between the third upper face and the fourth upper face, the first upper face is directly adjacent to the third upper face and the fourth upper face, and the second upper face is directly adjacent to the third upper face and the fourth upper face.

18. The light emitting device according to claim 10, further comprising: the one or more semiconductor laser elements are at least three semiconductor laser elements.

19. The light emitting device according to claim 10, wherein: the light reflective member is a microelectromechanical system or a photodiode, and the optical member is lens member.
